

DDR2 SO DIMM

TE Internal #: 1565917-4 SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, DDR2 SO DIMM

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DRAM Type: Double Data Rate (DDR) 2

Stack Height: 5.2 mm [.205 in]

Module Orientation: Right Angle

Number of Positions: 200

Centerline (Pitch): .6 mm [.024 in]

All DDR2 SO DIMM Sockets (30)



Features

Product Type Features

Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 2
Configuration Features	
Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200
Electrical Characteristics	
DRAM Voltage	1.8 V
Signal Characteristics	

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SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, DDR2 SO DIMM



Fjector LocationBoth EndsEjector LocationStainless SteelLatch MaterialTinLatch Plating MaterialGGRAMModule Key TypeSGRAMEjector TypeLockingConnector ProfileStandardContact FeaturesVemory CardPCB Contact Termination Area Plating MaterialGold FlashContact Mating Area Plating MaterialGold FlashContact Mating Area Plating MaterialGold FlashImmination FeaturesStandardImmination FeaturesScan-In		
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Contact Mating Area Plating Material Gold Flash Termination Features Insertion Style	Contact Base Material	Copper Alloy
Termination Features Insertion Style Cam-In	Contact Current Rating (Max)	.5 A
Insertion Style Cam-In	Contact Mating Area Plating Material	Gold Flash
	ermination Features	
Termination Method to Printed Circuit Board Surface Mount	Insertion Style	Cam-In
	Termination Method to Printed Circuit Board	Surface Mount

Mechanical Attachment

Mating Alignment Type	Standard Keying	
PCB Mount Retention	With	
PCB Mount Retention Type	Solder Peg	
Connector Mounting Type	Board Mount	
Housing Features		
Housing Material	High Temperature Thermoplastic	
Housing Color	Black	
Centerline (Pitch)	.6 mm[.024 in]	
Dimensions		
Stack Height	5.2 mm[.205 in]	
Row-to-Row Spacing	6.2 mm[.244 in]	
Usage Conditions		
Operating Temperature Range	-55 - 85 °C[-67 - 185 °F]	
Operation/Application		

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Circuit Application	Power
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	150
Packaging Method	Tape & Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, DDR2 SO DIMM



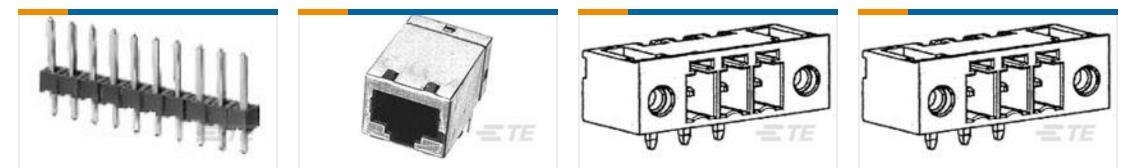


Also in the Series | DDR2 SO DIMM





Customers Also Bought



TE Part # 5-146276-2	TE Part # 5557789-1	TE Part # 1-284539-0	TE Part # 1-284539-2
02 MODII HDR SRST B/A .100CL	MJ,8POS,R/A,SHORTNG,PCBG	10 POS TERMI-BLOK 900 W.S.F 3,	12 POS TERMI-BLOK 900 W.S.F 3,
	IDH BB BB	THE REAL	
TE Part # 2007710-1	TE Part # 1-2176349-1	TE Part # 5787956-1	TE Part # 3-1768405-2
IMP100S,R,RA3P16C,RG,39	CRGCQ 2512 68R 1%	SOCKET ASSY IEEE1394	LBG-U-02933/EET

TE Part # 708511-2 ISOLAMES CU 3x9x0,8x2000

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Documents

Product Drawings EMBOSS ASSY DDR2 SODIMM SOCKET 200P 5.2H

English

CAD Files

Customer View Model ENG_CVM_CVM_1565917-4_D1.2d_dxf.zip

English

3D PDF

3D

Customer View Model ENG_CVM_CVM_1565917-4_D1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1565917-4_D1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions**of use.

Product Specifications Application Specification

English